

Applic. No.: 10/079,114

Amdt. Dated September 15, 2004

Reply to Office action of June 15, 2004

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of claims:**

Claim 1 (currently amended). An electronic component, comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an active upper side with a central portion and edge portions, a passive rear side, and a sawn edge;

said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having non-straight profile-sawn contours extending into said edge ~~portion~~ portions of said active upper side; and

a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours;

said central portion of said active upper side being uncovered by said plastics composition.

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Claim 2 (previously presented). An electronic component,  
comprising:

a semiconductor chip including a semiconductor material, said  
semiconductor chip having an active upper side, a passive rear  
side, and a sawn edge;

said sawn edge being formed of said semiconductor material and  
surrounding said semiconductor chip, said sawn edge having  
profile-sawn contours; and

a plastics composition forming a plastic edge, said plastic  
edge surrounding said sawn edge and being in a form-locking  
engagement with said profile-sawn contours;

said plastic edge having a rectangular cross section which is  
extended, toward said active upper side of said semiconductor  
chip, by a triangular area tapering to a point.

Claim 3 (currently amended). An electronic component,  
comprising:

a semiconductor chip including a semiconductor material, said  
semiconductor chip having an active upper side, a passive rear  
side, and a sawn edge;

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said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having profile-sawn contours; and

a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours[[]];

said plastic edge having a rectangular cross section with an additional rectangular area widening said rectangular cross section toward said active upper side of said semiconductor chip.

Claim 4 (original). The electronic component according to claim 1, wherein said plastic edge has a cross section formed with a notch at said active upper side.

Claim 5 (previously presented). An electronic component, comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an active upper side, a passive rear side, and a sawn edge;

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said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having profile-sawn contours; and

a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours;

said plastic edge having a U-shaped cross section with a relatively shorter leg and a relatively longer leg; and

said active upper side of said semiconductor chip having an edge region with a groove formed therein, said relatively shorter leg engaging in said groove, and said relatively longer leg forming an outer edge of said plastic edge.

Claim 6 (original). The electronic component according to claim 1, including an adhesion-promoting layer provided between said sawn edge and said plastics composition.

Claim 7 (original). The electronic component according to claim 6, wherein said adhesion-promoting layer includes at least one element selected from the group consisting of a zinc oxide and a chromium oxide.

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Claim 8 (cancelled).

Claim 9 (original). The electronic component according to claim 1, wherein said active upper side of said semiconductor chip includes an integrated circuit.

Claim 10 (original). The electronic component according to claim 1, wherein said active upper side of said semiconductor chip includes a contact sensor.

Claims 11-13 (cancelled).

Claim 14 (previously presented). An electronic component, comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an active upper side, a passive rear side, and a sawn edge;

said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having profile-sawn contours; and

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a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours;

said plastic edge having a rectangular cross section which is extended, toward said passive rear side of said semiconductor chip, by a triangular area tapering to a point.

Claim 15 (previously presented). An electronic component, comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an active upper side, a passive rear side, and a sawn edge;

said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having profile-sawn contours; and

a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours;

said plastic edge having a rectangular cross section with an additional rectangular area widening said rectangular cross

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section toward said passive rear side of said semiconductor chip.

Claim 16 (original). The electronic component according to claim 1, wherein said plastic edge has a cross section formed with a notch at said passive rear side.

Claim 17 (previously presented). An electronic component, comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an active upper side, a passive rear side, and a sawn edge;

said sawn edge being formed of said semiconductor material and surrounding said semiconductor chip, said sawn edge having profile-sawn contours; and

a plastics composition forming a plastic edge, said plastic edge surrounding said sawn edge and being in a form-locking engagement with said profile-sawn contours;

said plastic edge having a U-shaped cross section with a relatively shorter leg and a relatively longer leg; and

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said passive rear side of said semiconductor chip having an edge region with a groove formed therein, said relatively shorter leg engaging in said groove, and said relatively longer leg forming an outer edge of said plastic edge.

Claims 18-25 (Canceled).

Claim 26 (currently amended). ~~The~~ An electronic component ~~according to claim 1,~~ wherein comprising:

a semiconductor chip including a semiconductor material, said semiconductor chip having an said active upper side has with an edge portion, a passive rear side, and a sawn edge;

said sawn edge ~~is~~ being formed of said semiconductor material and ~~surrounds~~ surrounding said semiconductor chip; and

said sawn edge ~~has~~ having non-straight profile-sawn contours extending into said edge portion of said active upper side.